

Nanomate V-Heart

For Silicon



Nanomate
V-Heart

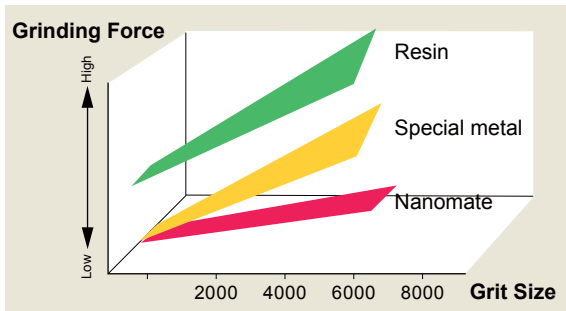
Suitable for rough grinding of deposited or sliced wafer

Strong diamond grit retention and high porosity vitrified bond, combined with a specially-shaped diamond layer, offers lower grinding force and improves grinding operations.

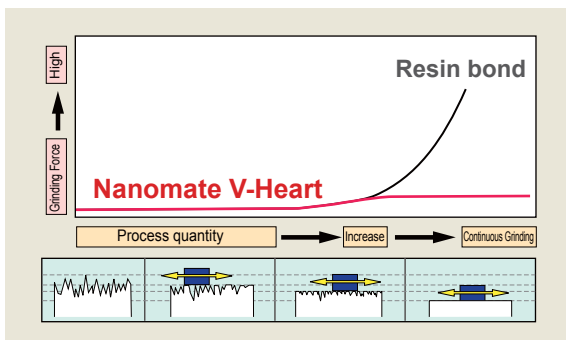
Achieves a flatness of less than 1µm on Ø300 Si wafer and makes possible to grind hard-to-cut materials, including semi-conductor, electrics, and other materials.

Grinding Force

Low grinding forces result in reduction of each load applied on workpiece and grinding machine.



Grinding Force is 1/10 of resin bonding wheel



Nanomate Premium

For Silicon



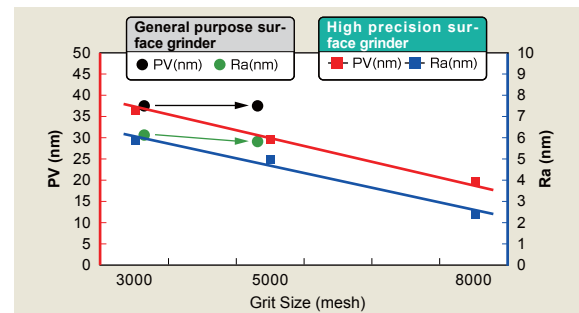
Nanomate
Premium

Suitable for mirror finish grinding of wafer and back side grinding of device wafer

Super-fine diamond grit and super-fine ceramics revolutionized the conventional wisdom with regard to grinding wheels. Application of both acquired material technology and production technology has allowed super-fine grinding.

Its effectiveness to reduce a grinding damaged layer of brittle material such as polish-reduction of Ø300mm silicon wafer and prevent cracks on a thin layer device wafer.

Relation between grit size and surface roughness



Grinding result by SD8000 Nanomate

